

ON Semiconductor®

FDD9407-F085

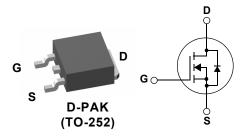
N-Channel Power Trench® MOSFET **40V**, **100A**, **2.0m**Ω

Features

- Typ $r_{DS(on)}$ = 1.6m Ω at V_{GS} = 10V, I_D = 80A
- Typ $Q_{g(tot)}$ = 86nC at V_{GS} = 10V, I_D = 80A
- UIS Capability
- RoHS Compliant
- Qualified to AEC Q101

Applications

- Automotive Engine Control
- Powertrain Management
- Solenoid and Motor Drivers
- Electronic Steering
- Integrated Starter/alternator
- Distributed Power Architectures and VRM
- Primary Switch for 12V Systems





MOSFET Maximum Ratings T_J = 25°C unless otherwise noted

Symbol	Parameter		Ratings	Units
V_{DSS}	Drain to Source Voltage		40	V
V_{GS}	Gate to Source Voltage		±20	V
	Drain Current - Continuous (V _{GS} =10) (Note 1)	T _C = 25°C	100	А
ID	Pulsed Drain Current	T _C = 25°C	See Figure4	A
E _{AS}	Single Pulse Avalanche Energy	(Note 2)	171	mJ
Ь	Power Dissipation		227	W
P_D	Derate above 25°C		1.52	W/°C
T _J , T _{STG}	Operating and Storage Temperature		-55 to + 175	°C
$R_{\theta JC}$	Thermal Resistance Junction to Case		0.66	°C/W
$R_{\theta JA}$	Maximum Thermal Resistance Junction to Ambient	(Note 3)	52	°C/W

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDD9407	FDD9407-F085	D-PAK(TO-252)	13"	12mm	2500 units

- 1: Current is limited by bondwire configuration.
- 1. Cutrent is inflited by borlowing configuration.

 2. Starting $T_J = 25^{\circ}C$, L = 0.08mH, $I_{AS} = 64$ A, $V_{DD} = 40$ V during inductor charging and $V_{DD} = 0$ V during time in avalanche

 3. $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta JC}$ is guaranteed by design while $R_{\theta JA}$ is determined by the user's board design. The maximum rating presented here is based on mounting on a 1 in² pad of 2oz copper.

Units

Max

Тур

Electrical Characteristics $T_J = 25^{\circ}C$ unless otherwise noted

Parameter

Off Characteristics							
B_{VDSS}	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V$	√ _{GS} = 0V	40	-	-	V
1	Drain to Source Leakage Current	V_{DS} =40 V ,	$T_{J} = 25^{\circ}C$	-	-	1	μΑ
IDSS		$V_{GS} = 0V$	$T_J = 175^{\circ}C(Note 4)$	-	-	1	mA
I _{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 20V$		-	-	±100	nA

Test Conditions

Min

On Characteristics

Symbol

V _{GS(th)}	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250 \mu A$		2.0	3.1	4.0	V
r _{DS(on)}	Il Irain to Source (In Registance	I _D = 80A,	$T_{J} = 25^{\circ}C$	-	1.6	2	mΩ
		V _{GS} = 10V	$T_J = 175^{\circ}C(Note 4)$		2.64	3.22	mΩ

Dynamic Characteristics

C _{iss}	Input Capacitance	V _{DS} = 25V, V _{GS} = 0V, f = 1MHz		-	6390	-	pF
C _{oss}	Output Capacitance			-	1580	-	pF
C _{rss}	Reverse Transfer Capacitance			-	95	-	pF
R_g	Gate Resistance	f = 1MHz		-	2.3	-	Ω
$Q_{g(ToT)}$	Total Gate Charge at 10V	V_{GS} = 0 to 10V	V _{DD} = 32V	-	86	112	nC
$Q_{g(th)}$	Threshold Gate Charge	V_{GS} = 0 to 2V	I _D = 80A	-	12	15.6	nC
Q_{gs}	Gate to Source Gate Charge		_	-	30	-	nC
Q_{gd}	Gate to Drain "Miller" Charge			-	15	-	nC

Switching Characteristics

t _{on}	Turn-On Time		-	-	120	ns
t _{d(on)}	Turn-On Delay Time		-	27	-	ns
t _r	Rise Time	V_{DD} = 20V, I_{D} = 80A, V_{GS} = 10V, R_{GEN} = 6 Ω	-	48	-	ns
t _{d(off)}	Turn-Off Delay Time		-	42	-	ns
t _f	Fall Time		-	18	-	ns
t _{off}	Turn-Off Time		-	-	97	ns

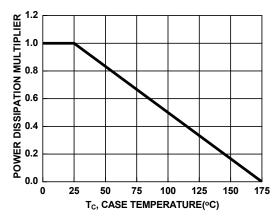
Drain-Source Diode Characteristics

V_{SD}	Source to Drain Diode Voltage	$I_{SD} = 80A, V_{GS} = 0V$	-	1	1.25	V
		$I_{SD} = 40A, V_{GS} = 0V$	-	-	1.2	V
T _{rr}	Reverse Recovery Time	$I_F = 80A$, $dI_{SD}/dt = 100A/\mu s$,	-	58	88	ns
Q _{rr}	Reverse Recovery Charge	V _{DD} =32V	-	83	143	nC

Notes:

4: The maximum value is specified by design at TJ = 175°C. Product is not tested to this condition in production.

Typical Characteristics



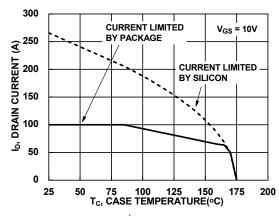


Figure 1. Normalized Power Dissipation vs Case Temperature

Figure 2. Maximum Continuous Drain Current vs
Case Temperature

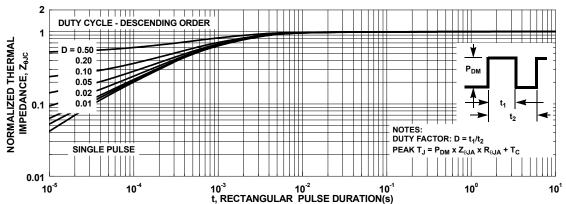


Figure 3. Normalized Maximum Transient Thermal Impedance

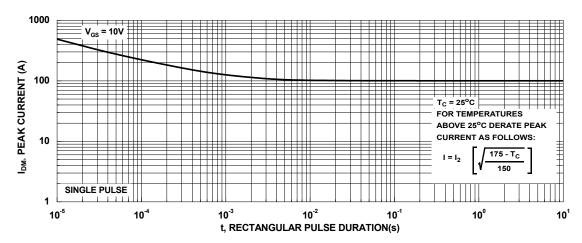


Figure 4. Peak Current Capability

Typical Characteristics

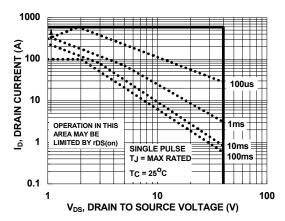


Figure 5. Forward Bias Safe Operating Area

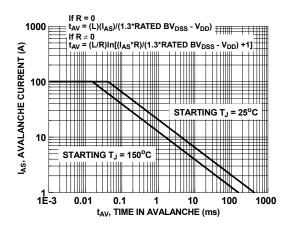


Figure 6. Unclamped Inductive Switching Capability

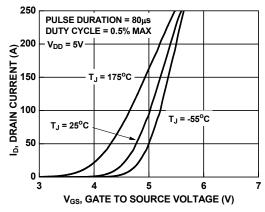


Figure 7. Transfer Characteristics

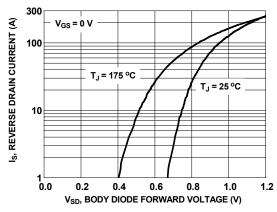


Figure 8. Forward Diode Characteristics

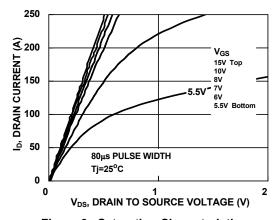


Figure 9. Saturation Characteristics

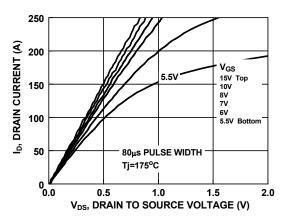


Figure 10. Saturation Characteristics

Typical Characteristics

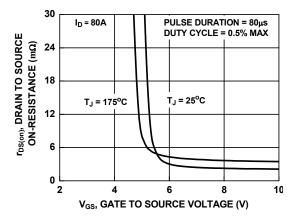


Figure 11. Rdson vs Gate Voltage

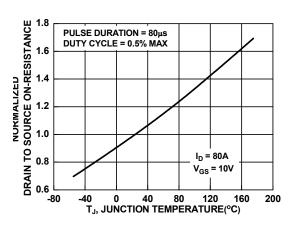


Figure 12. Normalized Rdson vs Junction Temperature

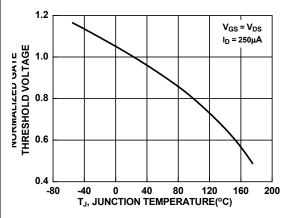


Figure 13. Normalized Gate Threshold Voltage vs
Temperature

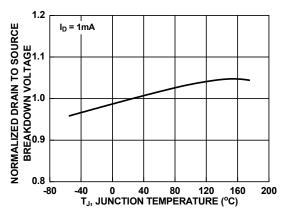


Figure 14. Normalized Drain to Source Breakdown Voltage vs Junction Temperature

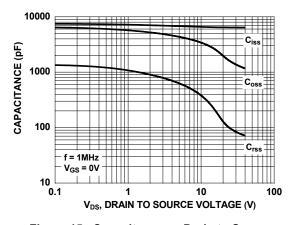


Figure 15. Capacitance vs Drain to Source Voltage

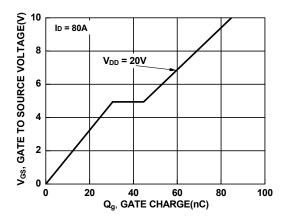


Figure 16. Gate Charge vs Gate to Source Voltage

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